

## Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-16. (Canceled)

17. (Currently Amended) A process of making a storage device comprising:

forming a first electrode disposed on a substrate;

forming a first organic adhesion layer disposed over the substrate and over the first electrode;

forming a ferroelectric polymer structure disposed above and on the first organic adhesion layer by forming a first crystalline ferroelectric polymer layer over the first organic adhesion layer, forming a spin-on ferroelectric polymer layer over the first crystalline ferroelectric polymer layer and forming a second crystalline ferroelectric polymer layer over the spin-on polymer layer;

forming a second organic adhesion layer disposed above and on the ferroelectric polymer structure; **[[and]]**

forming a second electrode disposed over the second organic adhesion layer.

18. (Original) The process according to claim 17, wherein forming a first organic adhesion layer over the substrate and over the first electrode is carried out by spin-on deposition.

19. (Original) The process according to claim 17, wherein forming a ferroelectric polymer structure over the first organic adhesion layer is carried out by spin-on deposition.

20. (Original) The process according to claim 17, wherein forming a second organic adhesion layer above and on the ferroelectric polymer structure is carried out by spin-on deposition.

21. (Original) The process according to claim 17, wherein forming a first organic adhesion layer and forming a second organic adhesion layer further comprise:  
depositing at least one hexamethyldisilazane composition over the substrate.

22. (Original) The process according to claim 17, further comprising:  
forming a first protective film over the first electrode; and  
forming a second protective film above and on the second organic adhesion layer.

23. (Canceled)

24. (Original) The process according to claim 17, wherein forming a first organic adhesion layer and forming a second organic adhesion layer each further comprises:

spinning on the adhesion promoter over the substrate for a period from about 5 seconds to about 20 seconds and in a rotational range from about 300 rpm to about 6000 rpm.

25. (Original) The process according to claim 17, wherein the ferroelectric polymer structure is selected from polyvinyl and polyethylene fluorides, polyvinyl and polyethylene chlorides, polyacrylonitriles, polyamides, copolymers thereof, and combinations thereof.

26. (Original) The process according to claim 17, further comprising:  
forming a first protective film above and on the first electrode; and  
forming a damascene structure in the substrate from the first electrode and the first protective film.

27-29. (Canceled)